

## Dual N-Channel 30-V (D-S) MOSFET

### PRODUCT SUMMARY

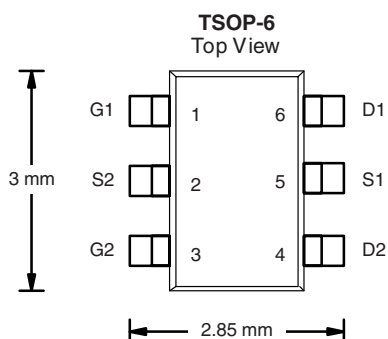
$V_{DS}$ (V)	$R_{DS(on)}$ ( $\Omega$ )	$I_D$ (A)
30	0.105 at $V_{GS} = 10$ V	$\pm 2.5$
	0.175 at $V_{GS} = 4.5$ V	$\pm 2.0$

### FEATURES

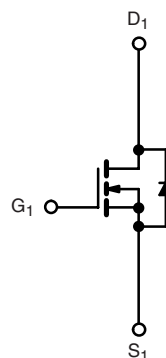
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFETs
- Compliant to RoHS Directive 2002/95/EC



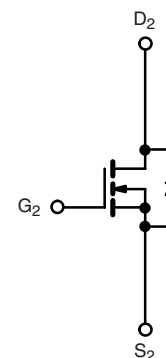
**RoHS**  
COMPLIANT  
**HALOGEN**  
**FREE**  
Available



**Ordering Information:** Si3948DV-T1-E3 (Lead (Pb)-free)  
Si3948DV-T1-GE3 (Lead (Pb)-free and Halogen-free)



N-Channel MOSFET



N-Channel MOSFET

### ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current ( $T_J = 150$ °C) <sup>a, b</sup>	$I_D$	$\pm 2.5$	A
		$\pm 2.0$	
Pulsed Drain Current (10 $\mu$ s Pulse Width)	$I_{DM}$	$\pm 8$	A
Continuous Source Current (Diode Conduction) <sup>a, b</sup>	$I_S$	1.05	A
Maximum Power Dissipation <sup>a, b</sup>	$P_D$	1.15	W
		0.73	
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	- 55 to 150	°C

### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>a</sup>	$R_{thJA}$	93	110	°C/W
		130	150	
Maximum Junction-to-Lead	$R_{thJL}$	75	90	°C/W

Notes:

a. Surface Mounted on FR4 board.

b.  $t \leq 5$  s.

<b>SPECIFICATIONS</b> $T_J = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$	1.0			V
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}$ , $V_{GS} = \pm 20\text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 24\text{ V}$ , $V_{GS} = 0\text{ V}$			1	$\mu\text{A}$
		$V_{DS} = 24\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_J = 55\text{ }^{\circ}\text{C}$			5	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} \geq 5\text{ V}$ , $V_{GS} = 10\text{ V}$	5			A
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$ , $I_D = 2.5\text{ A}$		0.085	0.105	$\Omega$
		$V_{GS} = 4.5\text{ V}$ , $I_D = 2.0\text{ A}$		0.140	0.175	
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = 10\text{ V}$ , $I_D = 2.5\text{ A}$		4.3		S
Diode Forward Voltage <sup>a</sup>	$V_{SD}$	$I_S = 1.05\text{ A}$ , $V_{GS} = 0\text{ V}$		0.81	1.1	V
<b>Dynamic<sup>b</sup></b>						
Total Gate Charge	$Q_g$	$V_{DS} = 15\text{ V}$ , $V_{GS} = 5.0\text{ V}$ , $I_D = 1.8\text{ A}$		2.1	3.2	nC
Gate-Source Charge	$Q_{gs}$			0.7		
Gate-Drain Charge	$Q_{gd}$			0.7		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 15\text{ V}$ , $R_L = 15\text{ }\Omega$ $I_D \cong 1\text{ A}$ , $V_{GEN} = 10\text{ V}$ , $R_G = 6\text{ }\Omega$		7	11	ns
Rise Time	$t_r$			9	14	
Turn-Off Delay Time	$t_{d(off)}$			13	20	
Fall Time	$t_f$			5	8	
Source-Drain Reverse Recovery Time	$t_{rr}$	$I_F = 1.05\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$		35	60	

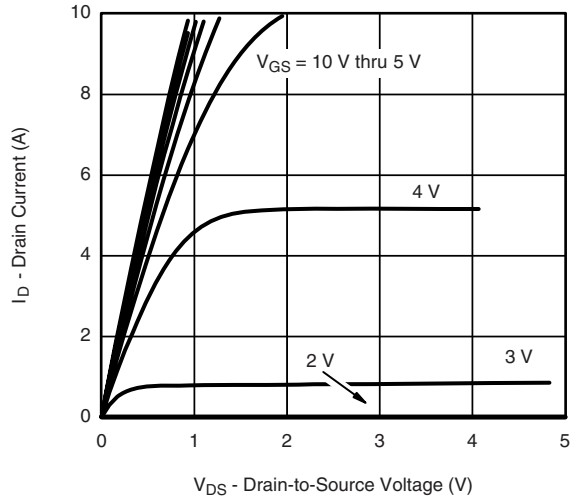
Notes:

a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .

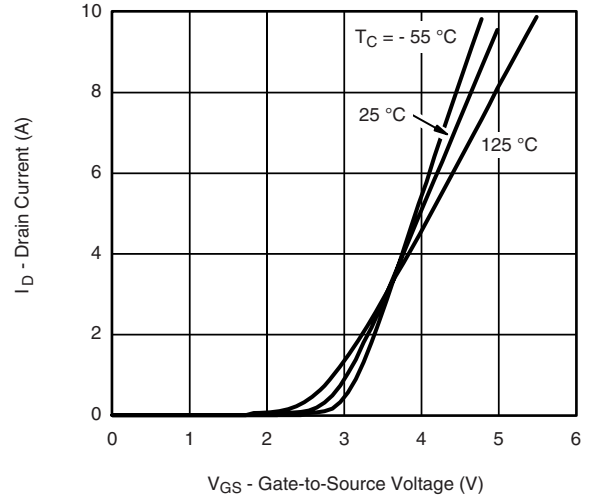
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

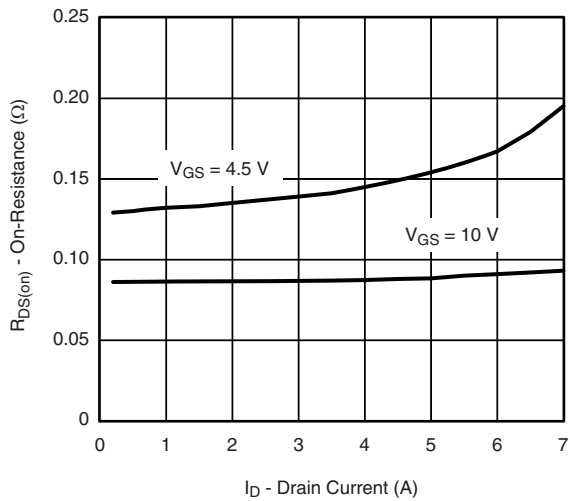
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



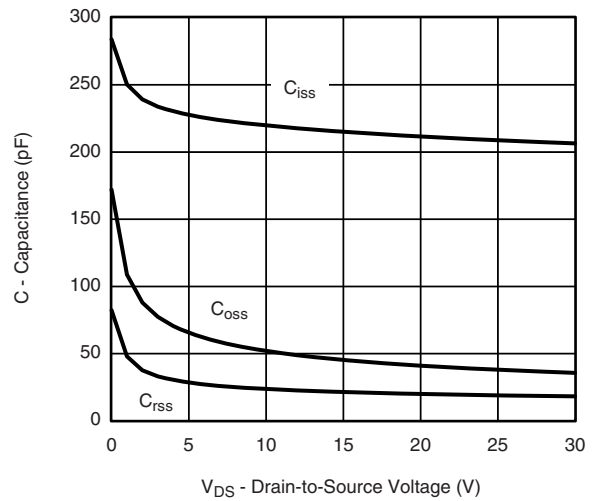
Output Characteristics



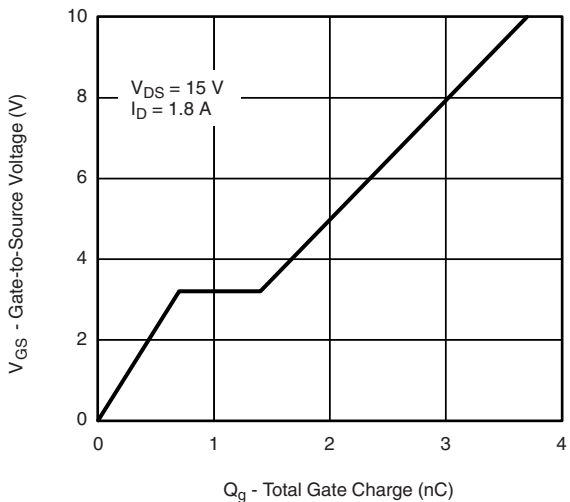
Transfer Characteristics



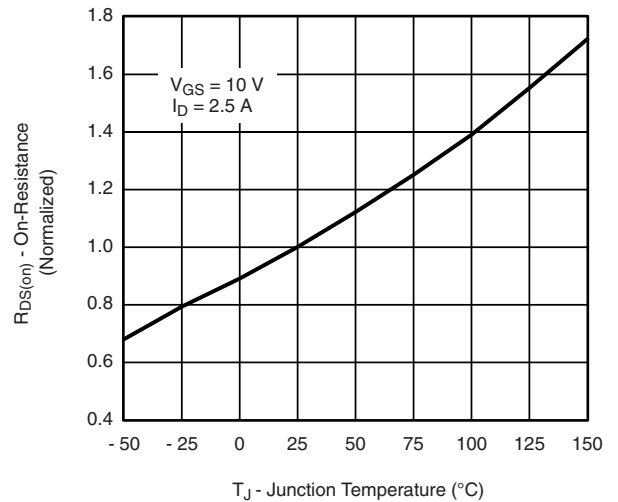
On-Resistance vs. Drain Current



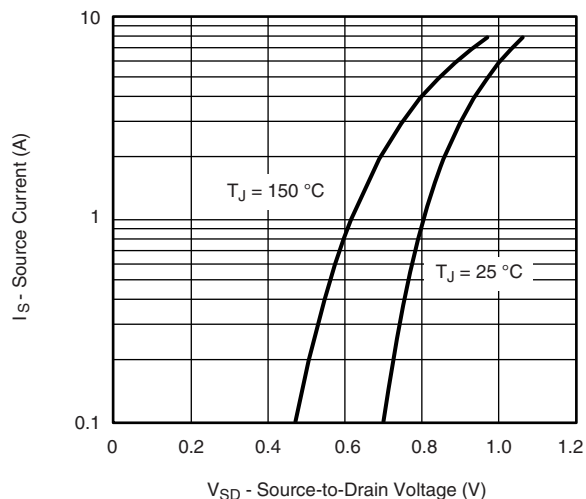
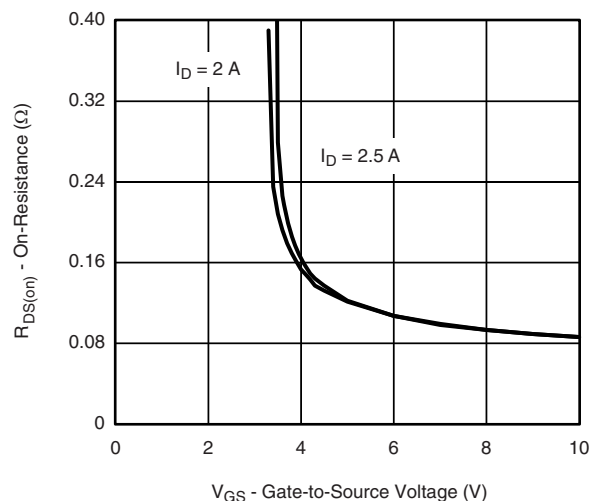
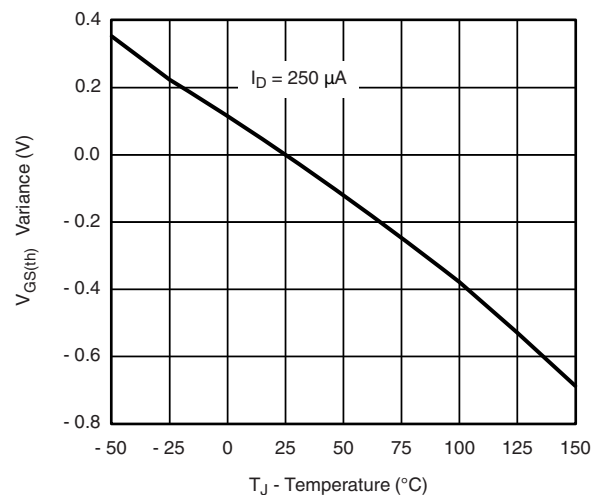
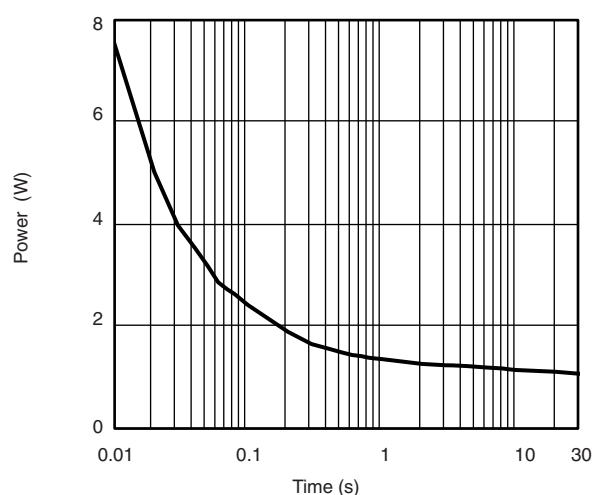
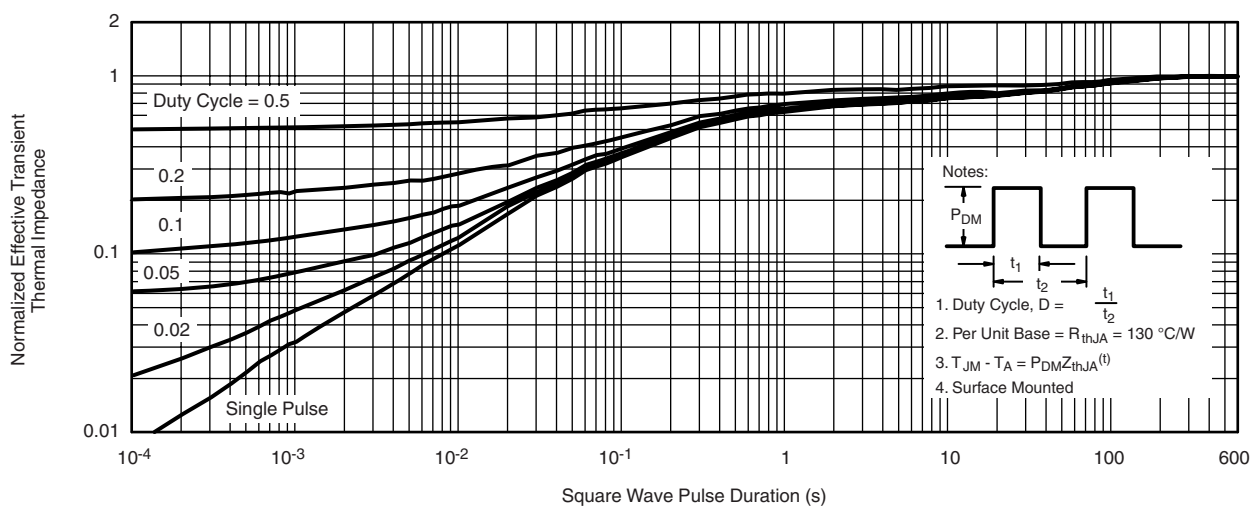
Capacitance



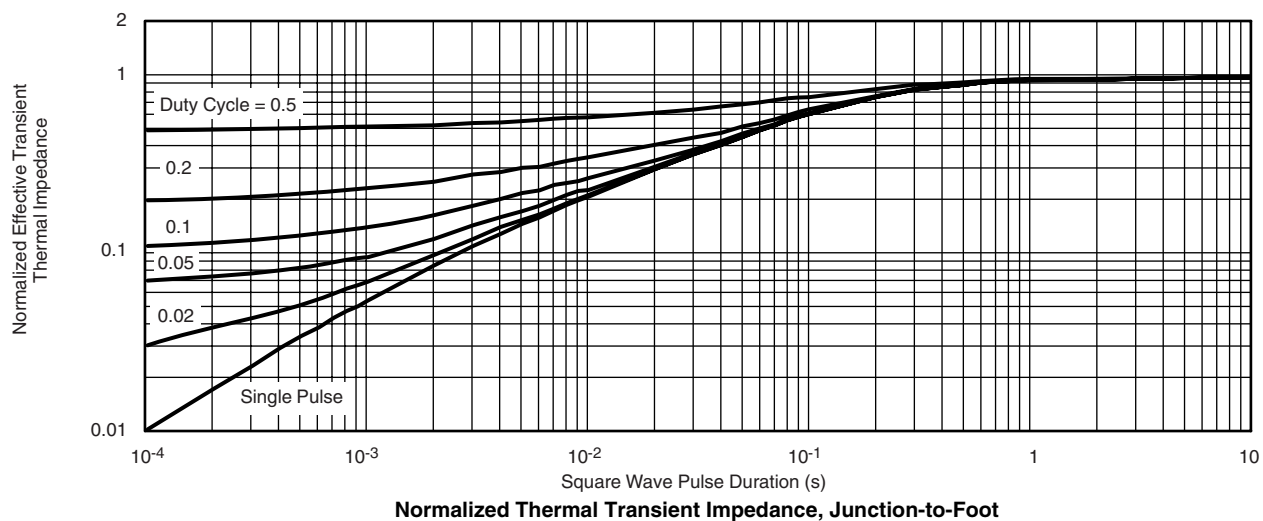
Gate Charge



On-Resistance vs. Junction Temperature

**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted**Source-Drain Diode Forward Voltage****On-Resistance vs. Gate-to-Source Voltage****Threshold Voltage****Single Pulse Power, Junction-to-Ambient****Normalized Thermal Transient Impedance, Junction-to-Ambient**

**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted



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